



Boschman Advanced Packaging Technology

Boschman is a high-tech, technology driven company, specialised in advanced back-end semiconductor packaging solutions. We are headquartered in the Netherlands with a system assembly facility in Singapore and expanding in China.

Stenograaf 3
6921 EX Duiven
The Netherlands

T +31 (0)26 319 4900

E info@boschman.nl

www.boschman.nl



Eef Boschman
Managing Director



Huub Claassen
Business Development Manager

We focus on Pressure Sintering and Transfer Molding, two technologies that are in high demand now as the world is converting to high levels of electrification, creating unprecedented opportunities for companies active in the power electronics supply chain.

Core to our strategy is a unique business model, “from Idea to Industrialization”, with 3 highly complementary activities:

- **Package Development:** co-development of semiconductor packages and processes, including concept and design for manufacturing (DFM), prototyping and engineering samples for our (end) customers. Historically this activity was mainly focused on MEMS and Sensors, but is currently shifting towards Power Modules and Inverters, driven by market demand in the xEV segment.
- **Assembly Services:** small to medium volume micro assembly of MEMS, Sensors and Power Modules, with a fully equipped inhouse lab (from wafer dicing to die attach bonding, molding and laser marking). For higher production volumes, we can support to transfer the production to in-house production or high-volume OSAT.
- **Production Equipment:** pressure sintering & transfer molding equipment, a range of systems from R&D Labs to High Volume production solutions.